



13

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re the application of:

Applicant :	Loi Nguyen	Docket No :	93-C-077C2
Serial No :	09/712827	Group No :	2814
Filed :	November 14, 2000	Examiner :	Long Pham
For :	Method And Interlevel Dielectric Structure For Improved Metal Step Coverage	Confirmation No :	4608

## TRANSMITTAL LETTER

Mail Stop Issue Fee  
Attention: Official Draftsman  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Notice of Allowability (PTO-37) mailed December 24, 2003, for the above-identified patent application, please find enclosed for filing two (2) sheets of formal drawings.

The Commissioner is hereby authorized to charge any fees which may be required to Deposit Account No. 19-1353. A duplicate copy of this sheet is enclosed.

Respectfully submitted

Mario J. Donato, Jr.  
Reg. No. 37,816  
Attorney for Applicant

STMicroelectronics, Inc.  
1310 Electronics Drive/MS 2346  
Carrollton, TX 75006  
972-466-7503

### CERTIFICATE OF MAILING 37 CFR 1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail with sufficient postage, in an enveloped addressed to: Mail Stop Issue Fee Attention: Official Draftsman Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-14501 on the date below:

March 19, 2004  
Date

Angie Rodriguez  
Signature